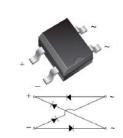


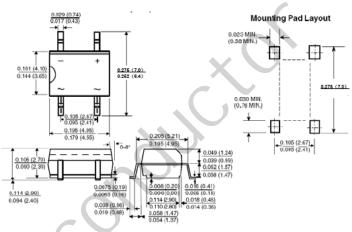
Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ Glass passivated chip junctions
- High surge overload rating:35A peak
- Saves space on printed circuit boards
- ♦ High temperature soldering guaranteed:260 °C/10 seconds



Mechanical Data

- Case:Molded plastic body over passivated junctions
- Terminals: plated leads solderable per MIL-STD-750, Method 2026
- Mounting Position:Any
- Weight:0.078 oz.,0.22g



Maximum Ratings & Electrical Characteristics

Parameter	Symbol	MB2S	MB4S	MB6S	MB8S	MB10S	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V
Maximum Average forward output current (see Fig.1) on glass-epoxy P.C.B on aluminum substrate	I _{F(AV)}			0.5 ⁽¹⁾ 0.8 ⁽²⁾			A
Peak forward surge current 8.3 MS single HALF sine-way superimposed on rated load (JEDEC Method)	I _{FSM}			35			А
Rating for fusig (t<8.3ms)	l ² t			5			A ² sec
Maximum instantaneous forward voltage drop per leg at 0.4A	VF			1.00			v
Maximum DC reverse current at TA=25℃ rated DC blocking voltage per leg TA=125℃	IR			5 100			μΑ
Typical thermal resistance per leg	R _{θJA} R _{θJA} R _{θJL}			85 ⁽¹⁾ 70 ⁽²⁾ 20 ⁽¹⁾			°C/W
Typical junction capacitance per at 4.0V,1.0MHz	Cj			13			pF
Operating junction and storage temperature range	$T_{J,T_{STG}}$			-55 to +150			°C

Notes: 1. On glass epoxy P.C.B. mounted on 0.05×0.05"(1.3×1.3mm) pads

 $\text{2. On aluminum substrate P.C.B.} whith an area of 0.8 \times 0.8" (20 \times 20 \text{mm}) \text{ mounted on } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05" (1.3 \times 1.3 \text{mm}) \text{ solder pad } 0.05 \times 0.05 \times 0.05 \times 0.05 \text{ solder pad } 0.05 \times 0.05 \times 0.05 \times 0.05$



Ratings and Characteristics Curves

(TA = 25° C unless otherwise noted)

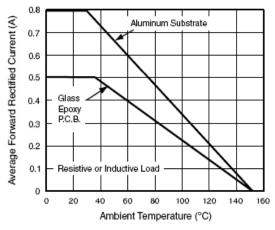


Figure 1.Derating Curve for Output Rectified Current

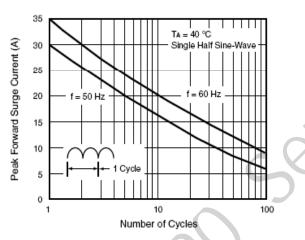


Figure 2.Maximum Non-Repetitive Peak Forward Surge Current Per Leg

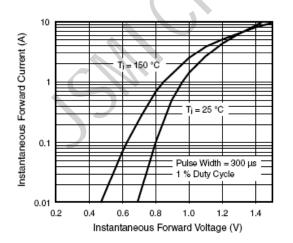


Figure 3. Typical Forward Voltage Characteristics Per Leg

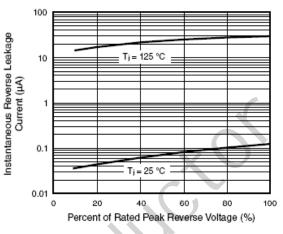


Figure 4.Typical Reverse Leakage Characteristics Per Leg

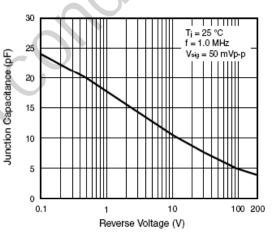


Figure 5.Typical Junction Capacitance Per Leg